



Search ...

PRODUCTS | APPLICATIONS | DESIGN SUPPORT | TRAINING | SAMPLE AND
BUY | ABOUT US | CONTACT US | myMicrochip Login

Product Change Notification - JAON-04DHCS000 (Printer Friendly)

Date:	10 Mar 2016
Product Category:	SMSC
Notification subject:	CCB 2512 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 0.18 and 0.16um GF wafer technologies available in 36L VQFN package at ANAC assembly site.
Notification text:	PCN Status: Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 and 0.16um GF wafer technologies available in 36L VQFN package at ANAC assembly site.

Pre Change:

Palladium coated copper wire (PdCu) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ANAC assembly site	ANAC assembly site
Wire material	PdCu wire	CuPdAu wire
Die attach material	8290	8290
Molding compound material	G700	G700
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Reason for Change:

To improve productivity and qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

June 30, 2016 (date code: 1626)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	March 2016					----->	May 2016				June 2016			
	09	10	11	12	13		18	19	20	21	22	23	24	25
WW														
Initial PCN Issue Date		X												
Qual Report Availability											X			
Final PCN Issue Date											X			
Implementation Date														

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

March 10, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-04DHCS000_Qual_Plan.pdf](#)
- [PCN_JAON-04DHCS000_Affected_CPN.pdf](#)
- [PCN_JAON-04DHCS000_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

[Products](#) | [Applications](#) | [Design Support](#) | [Training](#) |
[Sample and Buy](#) | [About Us](#) | [Contact Us](#) | [Legal](#) | [Investors](#) |
[Careers](#) | [Support](#)

©Copyright 1998-2016 Microchip Technology Inc. All rights reserved.
Shanghai ICP Recordal No.09049794